

FORM PTO 1449 (modified)

U.S. DEPARTMENT OF COMMERCE  
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GROUP 2817

## U.S. PATENT DOCUMENTS

*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
BS	AA	5,515,015	5/1996	Nakata	333	132	
BS	AB	2003/0058066 2003/058066	3/2003	Taniguchi et al.	333	193	
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						

## FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES NO
BS	AJ	10-313229	11/1998	JP			Abstract
BS	AK	7-106811	4/1995	JP			Abstract
	AL						
	AM						
	AN						

## OTHER DOCUMENT(S) (Including Author, Title, Date, Pertinent Pages, Etc.)

BS	AO	G. Ponchak et al., "The Use of Metal Filled Via Holes for Improving Isolation in LTCC RF and Wireless Multichip Packages, IEEE TRANSACTIONS ON ADVANCED PACKAGING, vol. 23, no. 1, February 2000, pp. 88-99
	AP	
	AQ	

EXAMINER /Barbara Summons/

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